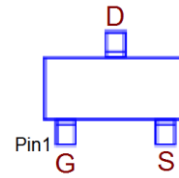
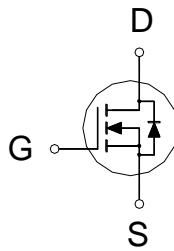




**PRODUCT SUMMARY**

$V_{(BR)DSS}$	$R_{DS(ON)}$	$I_D$
30V	20m $\Omega$	6.2A



G. GATE  
D. DRAIN  
S. SOURCE

**ABSOLUTE MAXIMUM RATINGS ( $T_A = 25\text{ }^\circ\text{C}$  Unless Otherwise Noted)**

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNITS
Drain-Source Voltage		$V_{DS}$	30	V
Gate-Source Voltage		$V_{GS}$	$\pm 20$	V
Continuous Drain Current	$T_A = 25\text{ }^\circ\text{C}$	$I_D$	6.2	A
	$T_A = 70\text{ }^\circ\text{C}$		5	
Pulsed Drain Current <sup>1</sup>		$I_{DM}$	30	
Power Dissipation <sup>3</sup>	$T_A = 25\text{ }^\circ\text{C}$	$P_D$	1.3	W
	$T_A = 70\text{ }^\circ\text{C}$		0.8	
Operating Junction & Storage Temperature Range		$T_j, T_{stg}$	-55 to 150	$^\circ\text{C}$

**THERMAL RESISTANCE RATINGS**

THERMAL RESISTANCE		SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Ambient <sup>2</sup>	$t \leq 10\text{ s}$	$R_{\theta JA}$		90	$^\circ\text{C} / \text{W}$
	Steady-State	$R_{\theta JA}$		146	
Junction-to-Case		$R_{\theta JC}$		60	

<sup>1</sup>Pulse width limited by maximum junction temperature, Ratings are based on low frequency and duty cycles to keep initial  $T_j=25\text{ }^\circ\text{C}$ .

<sup>2</sup>The value of  $R_{\theta JA}$  is measured with the device mounted on 1in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with  $T_A = 25\text{ }^\circ\text{C}$ .

<sup>3</sup>The Power dissipation is based on  $R_{\theta JA} t \leq 10\text{ s}$  value.

**ELECTRICAL CHARACTERISTICS ( $T_j = 25\text{ }^\circ\text{C}$ , Unless Otherwise Noted)**

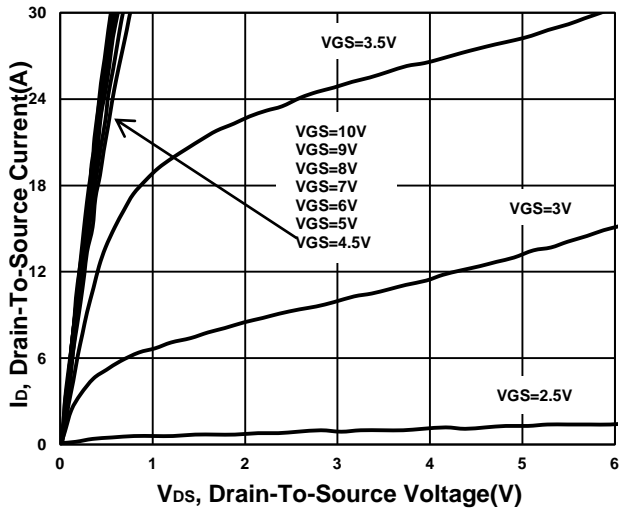
PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
<b>STATIC</b>						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0\text{ V}, I_D = 250\mu\text{A}$	30			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	1.3	1.75	2.3	
Gate-Body Leakage	$I_{GSS}$	$V_{DS} = 0\text{ V}, V_{GS} = \pm 20\text{ V}$			$\pm 100$	nA
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 24\text{ V}, V_{GS} = 0\text{ V}$			1	$\mu\text{A}$
		$V_{DS} = 20\text{ V}, V_{GS} = 0\text{ V}, T_j = 55\text{ }^\circ\text{C}$			10	

Drain-Source On-State Resistance <sup>1</sup>	$R_{DS(ON)}$	$V_{GS} = 4.5V, I_D = 5A$	23	31	mΩ
		$V_{GS} = 10V, I_D = 5A$	17	20	
Forward Transconductance <sup>1</sup>	$g_{fs}$	$V_{DS} = 5V, I_D = 5A$	26		S
<b>DYNAMIC</b>					
Input Capacitance	$C_{iss}$	$V_{GS} = 0V, V_{DS} = 15V, f = 1MHz$	329		pF
Output Capacitance	$C_{oss}$		70		
Reverse Transfer Capacitance	$C_{rss}$		45		
Total Gate Charge <sup>2</sup>	$Q_g$	$V_{DS} = 15V, V_{GS} = 10V, I_D = 5A$	7.8		nC
Gate-Source Charge <sup>2</sup>	$Q_{gs}$		1.2		
Gate-Drain Charge <sup>2</sup>	$Q_{gd}$		2.3		
Turn-On Delay Time <sup>2</sup>	$t_{d(on)}$	$V_{DS} = 15V, I_D \cong 5A, V_{GS} = 10V, R_{GEN} = 6\Omega$	17		nS
Rise Time <sup>2</sup>	$t_r$		17		
Turn-Off Delay Time <sup>2</sup>	$t_{d(off)}$		37		
Fall Time <sup>2</sup>	$t_f$		18		
<b>SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (T<sub>J</sub> = 25 °C)</b>					
Continuous Current	$I_S$			1.1	A
Forward Voltage <sup>1</sup>	$V_{SD}$	$I_F = 5A, V_{GS} = 0V$		1.1	V
Reverse Recovery Time	$t_{rr}$	$I_F = 5A, dI_F/dt = 100A / \mu S$	10		nS
Reverse Recovery Charge	$Q_{rr}$		2.6		nC

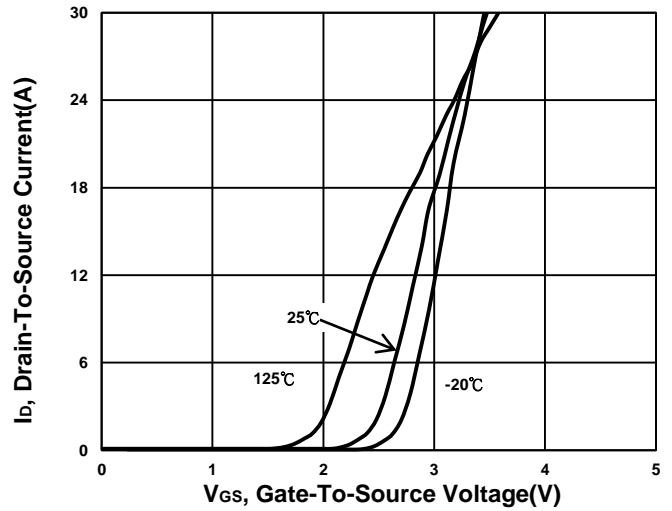
<sup>1</sup>Pulse test : Pulse Width ≤ 300 μsec, Duty Cycle ≤ 2%.

<sup>2</sup>Independent of operating temperature.

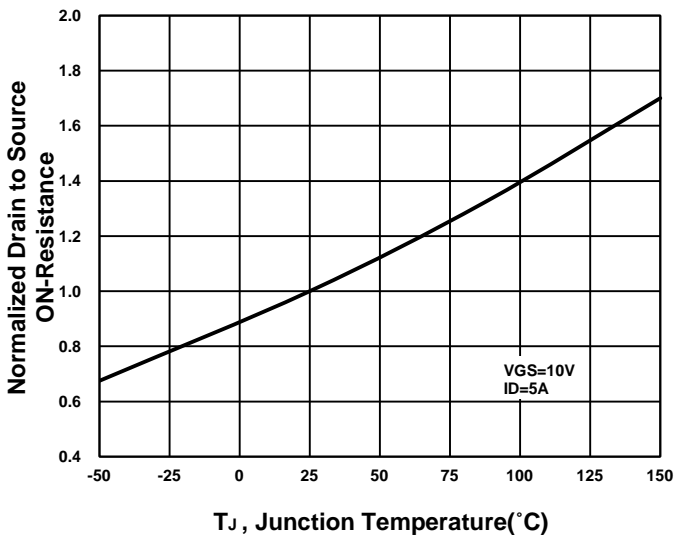
**Output Characteristics**



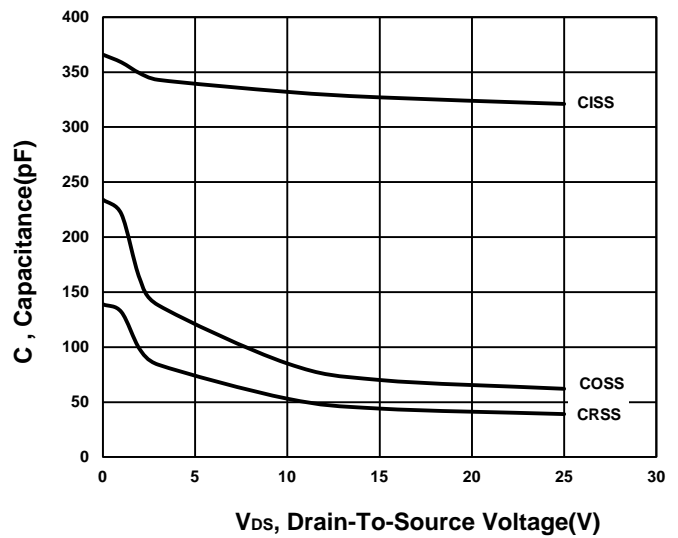
**Transfer Characteristics**



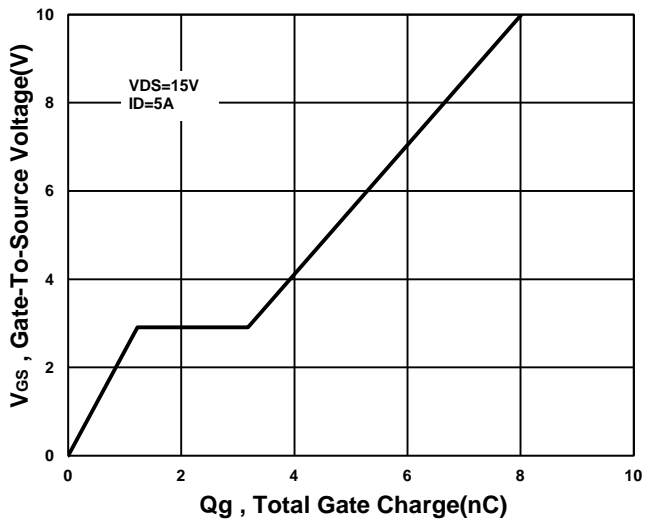
**On-Resistance VS Temperature**



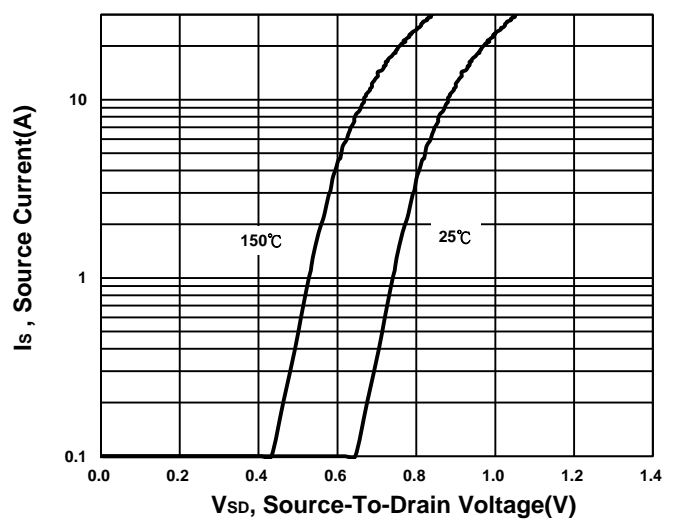
**Capacitance Characteristic**



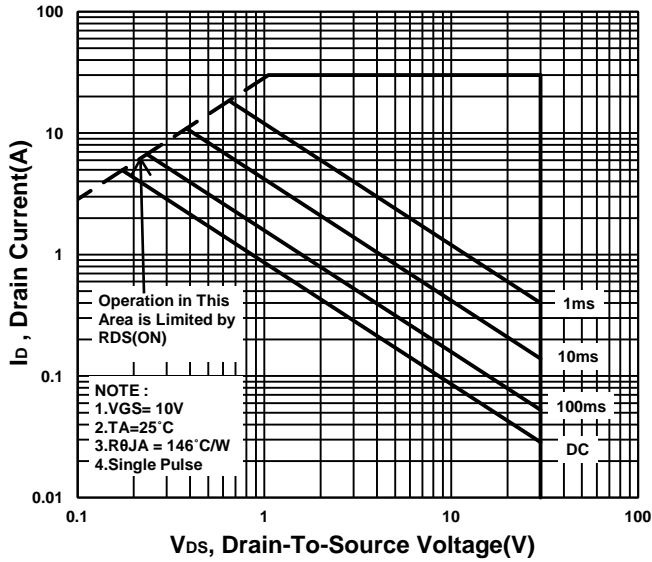
**Gate charge Characteristics**



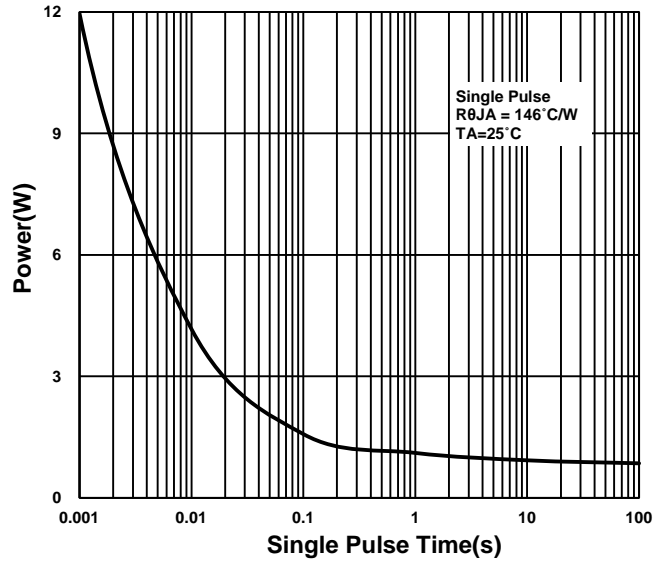
**Source-Drain Diode Forward Voltage**



**Safe Operating Area**



**Single Pulse Maximum Power Dissipation**



**Transient Thermal Response Curve**

